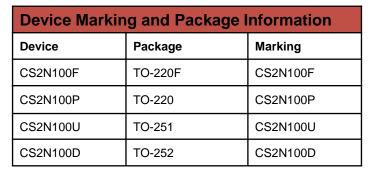
### 1000V N-Channel MOSFET

#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)





<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted								
Parameter	Symbol		l locit					
		TO-220F	TO-220	TO-251	TO-252	Unit		
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	1000			V			
Continuous Drain Current	I <sub>D</sub>	2			А			
Pulsed Drain Current (note1)	I <sub>DM</sub>	8			Α			
Gate-Source Voltage	V <sub>GSS</sub>	±30			V			
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	45			mJ			
Avalanche Current (note1)	I <sub>AS</sub>	3			Α			
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	27			mJ			
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	36 75		W				
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C				

Thermal Resistance						
Parameter	Symbol	Value				11!1
		TO-220F	TO-220	TO-251	TO-252	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	3.47	1.67		°C/W	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60			



<b>Specifications</b> $T_J = 25^{\circ}C$ , ur	less othe	rwise noted					
Parameter	Symbol	Test Conditions	Value			Unit	
r al allietei	Symbol	rest conditions	Min.	Тур.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	1000			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 1000V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$	ŀ		±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	٧	
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 1.0A$		6	7.2	Ω	
Dynamic							
Input Capacitance	C <sub>iss</sub>	V - 0V		419		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		45			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		9			
Total Gate Charge	$Q_g$			16		nC	
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 800V, I_{D} = 2.0A,$ $V_{GS} = 15V$		2			
Gate-Drain Charge	$Q_{gd}$	65		8			
Turn-on Delay Time	t <sub>d(on)</sub>			36		ns	
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 500V, I_{D} = 2.0A,$ $R_{G} = 25 \Omega$		12			
Turn-off Delay Time	t <sub>d(off)</sub>			100			
Turn-off Fall Time	t <sub>f</sub>			43			
Drain-Source Body Diode Character	istics						
Continuous Body Diode Current	I <sub>s</sub>	T 05.00			2	А	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			8		
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 1.0A$ , $V_{GS} = 0V$			1.4	V	
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 2.0A,$		432.5		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	$di_{F}/dt = 100A / \mu s$		424		nC	

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 10.0mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%

#### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )

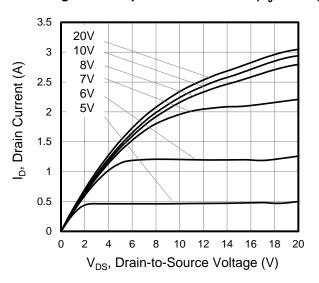


Figure 3. Drain Current vs. Temperature

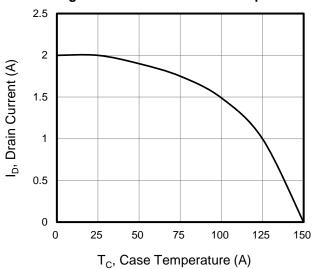


Figure 5. Transfer Characteristics

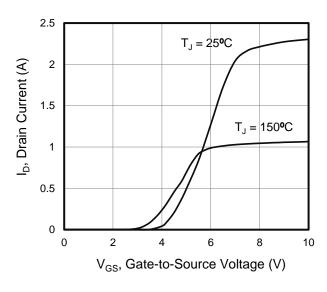


Figure 2. Body Diode Forward Voltage

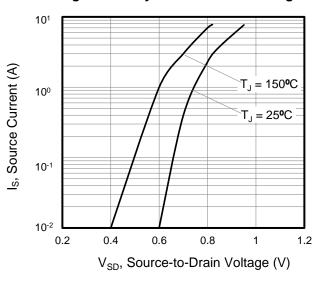


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

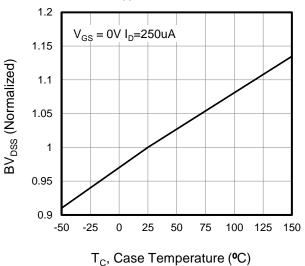
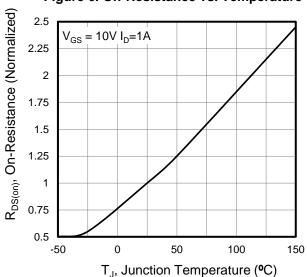


Figure 6. On-Resistance vs. Temperature



### **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

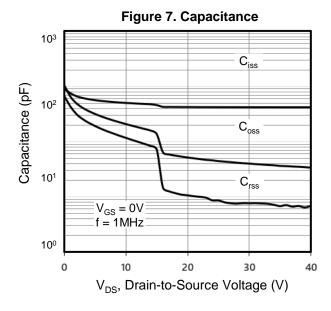


Figure 8. Gate Charge

V<sub>DD</sub> = 200V

V<sub>DD</sub> = 500V

V<sub>DD</sub> = 800V

V<sub>DD</sub> = 800V

V<sub>DD</sub> = 800V

Q<sub>g</sub>, Total Gate Charge (nC)

Figure 9. Transient Thermal Impedance TO-220F

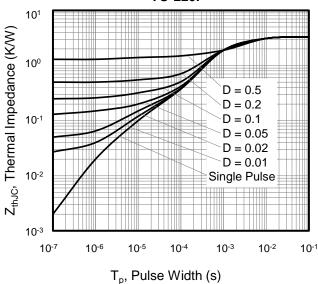


Figure 10. Transient Thermal Impedance TO-220,TO-251,TO-252

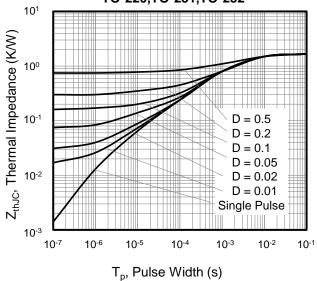


Figure A: Gate Charge Test Circuit and Waveform

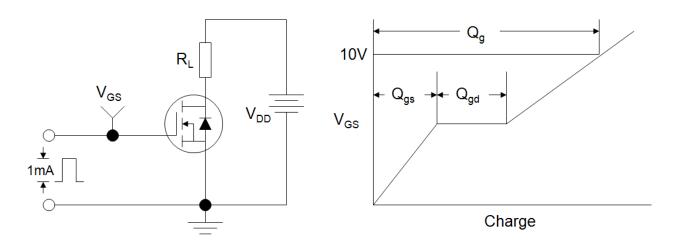


Figure B: Resistive Switching Test Circuit and Waveform

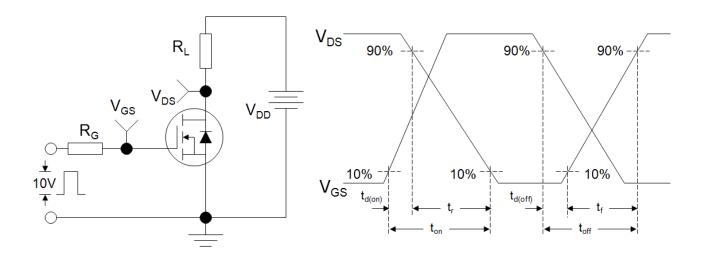
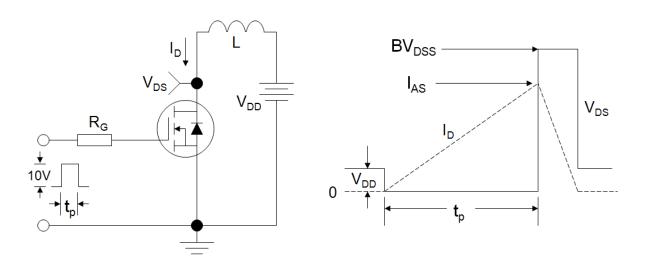
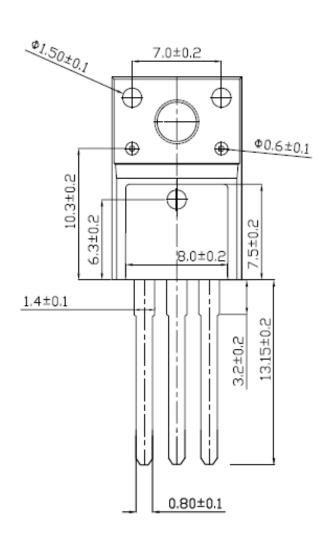
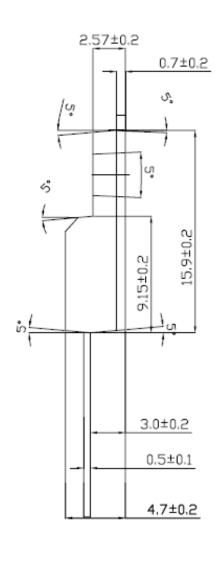


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



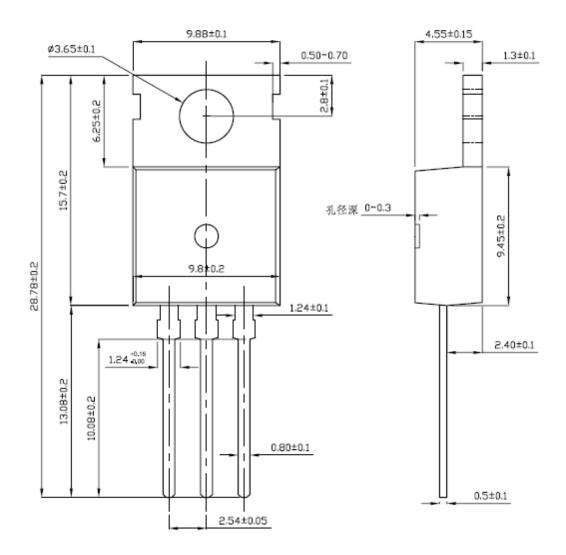
## **TO-220F**





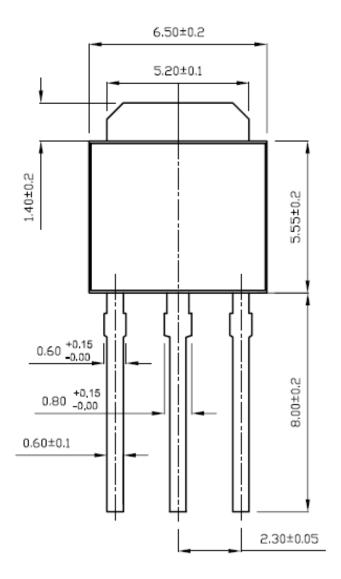


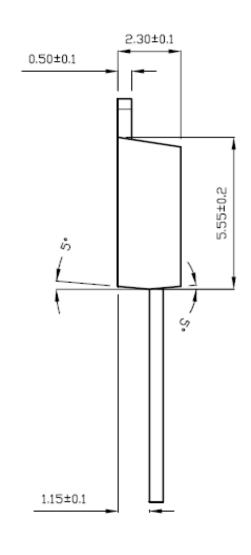
## **TO-220**



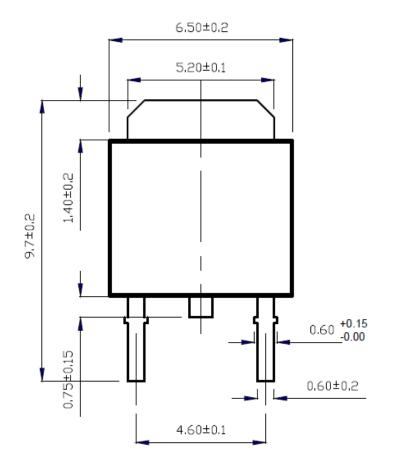


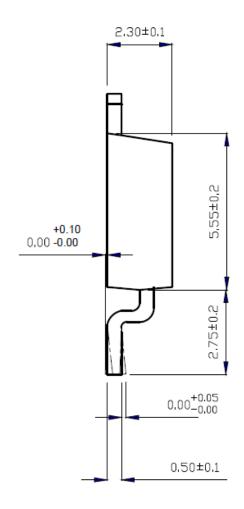
## TO-251





## **TO-252**







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